

Notice of References Cited	Application/Control No.	Applicant(s)/Patent Under Reexamination UCHIBORI, CHIHIRO	
	Examiner Granvill D Lee, Jr	Art Unit 2825	Page 1 of 1

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*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	A	US-4751349	10-1986	Kim et al.	174/68.5
	B	US-6249055	02-1998	Dubin	257/758
	C	US-6284656	08-1998	Farrar	438/687
	D	US-5677244	05-1996	Venkatraman	437/198
	E	US-5539256	02-1995	Mikagi	257/763
	F	US-5895231	10-1997	Choi et al.	438/106
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NON-PATENT DOCUMENTS

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	Berti et al. "Characterization of a PVD-TiN as the diffusion barrier/adhesion promoter..." Sematech Research pg. 118-119
	V	Moussavi et al. "Comparison of barrier materials and deposition process of copper integration" IEEE IITC 98-295 0-7803-4285-2/98 pg. 295-297.
	W	Baumann et al. "Tin/W double layers as a barrier system for use in Cu metallization" Materials for advanced metallization pg. 128-129
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*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.